THE DATASHEET OF

IRGPC50UD2

PD - 9.802A

IRGPC50UD2

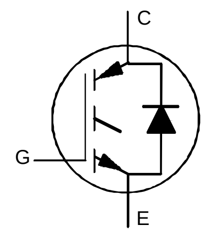
International Rectifier

INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE

UltraFast CoPack IGBT

Features

- Switching-loss rating includes all "tail" losses
- HEXFRED™ soft ultrafast diodes
- Optimized for high operating frequency (over 5kHz) See Fig. 1 for Current vs. Frequency curve



n-channel

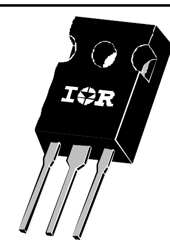
V_{CES} = 600V

$V_{CE(sat)} \leq 3.0V$

@V_{GE} = 15V, I_C = 27A

Description

Co-packaged IGBTs are a natural extension of International Rectifier's well known IGBT line. They provide the convenience of an IGBT and an ultrafast recovery diode in one package, resulting in substantial benefits to a host of high-voltage, high-current, motor control, UPS and power supply applications.



TO-247AC

Absolute Maximum Ratings

	Parameter	Max.	Units
V_{CES}	Collector-to-Emitter Voltage	600	V
I_C @ T_C = 25°C	Continuous Collector Current	55	A
I_C @ T_C = 100°C	Continuous Collector Current	27	
I_{CM}	Pulsed Collector Current ①	220	
I_{LM}	Clamped Inductive Load Current ②	220	
I_F @ T_C = 100°C	Diode Continuous Forward Current	25	
I_{FM}	Diode Maximum Forward Current	220	
V_{GE}	Gate-to-Emitter Voltage	± 20	V
P_D @ T_C = 25°C	Maximum Power Dissipation	200	W
P_D @ T_C = 100°C	Maximum Power Dissipation	78	
T_J T_{STG}	Operating Junction and Storage Temperature Range	-55 to +150	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in. (1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw.	10 lbf•in (1.1 N•m)	

Thermal Resistance

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$	Junction-to-Case - IGBT	—	—	0.64	°C/W
$R_{\theta JC}$	Junction-to-Case - Diode	—	—	0.83	
$R_{\theta CS}$	Case-to-Sink, flat, greased surface	—	0.24	—	
$R_{\theta JA}$	Junction-to-Ambient, typical socket mount	—	—	40	
Wt	Weight	—	6 (0.21)	—	g (oz)

Revision 1

Electrical Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions	
$V_{(BR)CES}$	Collector-to-Emitter Breakdown Voltage ③	600	—	—	V	V_{GE} = 0V, I_C = 250µA	
$\Delta V_{(BR)CES}/\Delta T_J$	Temp. Coeff. of Breakdown Voltage	—	0.60	—	V/°C	V_{GE} = 0V, I_C = 1.0mA	
$V_{CE(on)}$	Collector-to-Emitter Saturation Voltage	—	1.9	3.0	V	I_C = 27A	V_{GE} = 15V
		—	2.4	—		I_C = 55A	See Fig. 2, 5
		—	1.9	—		I_C = 27A, T_J = 150°C	
$V_{GE(th)}$	Gate Threshold Voltage	3.0	—	5.5		V_{CE} = V_{GE}, I_C = 250µA	
$\Delta V_{GE(th)}/\Delta T_J$	Temp. Coeff. of Threshold Voltage	—	-13	—	mV/°C	V_{CE} = V_{GE}, I_C = 250µA	
g_{fe}	Forward Transconductance ④	16	24	—	S	V_{CE} = 100V, I_C = 27A	
I_{CES}	Zero Gate Voltage Collector Current	—	—	250	µA	V_{GE} = 0V, V_{CE} = 600V	
		—	—	6500		V_{GE} = 0V, V_{CE} = 600V, T_J = 150°C	
V_{FM}	Diode Forward Voltage Drop	—	1.3	1.7	V	I_C = 25A	See Fig. 13
		—	1.2	1.5		I_C = 25A, T_J = 150°C	
I_{GES}	Gate-to-Emitter Leakage Current	—	—	±100	nA	V_{GE} = ±20V	

Switching Characteristics @ T_J = 25°C (unless otherwise specified)

	Parameter	Min.	Typ.	Max.	Units	Conditions		
Q_g	Total Gate Charge (turn-on)	—	110	140	nC	I_C = 27A		
Q_{ge}	Gate - Emitter Charge (turn-on)	—	17	21		V_{CC} = 400V		
Q_{gc}	Gate - Collector Charge (turn-on)	—	53	70		See Fig. 8		
$t_{d(on)}$	Turn-On Delay Time	—	73	—	ns	T_J = 25°C		
t_r	Rise Time	—	71	—		I_C = 27A, V_{CC} = 480V		
$t_{d(off)}$	Turn-Off Delay Time	—	210	320		V_{GE} = 15V, R_G = 5.0Ω		
t_f	Fall Time	—	150	280		Energy losses include "tail" and		
E_{on}	Turn-On Switching Loss	—	1.4	—	mJ	diode reverse recovery.		
E_{off}	Turn-Off Switching Loss	—	1.6	—		See Fig. 9, 10, 11, 18		
E_{ts}	Total Switching Loss	—	3.0	4.5				
$t_{d(on)}$	Turn-On Delay Time	—	73	—	ns	T_J = 150°C, See Fig. 9, 10, 11, 18		
t_r	Rise Time	—	67	—		I_C = 27A, V_{CC} = 480V		
$t_{d(off)}$	Turn-Off Delay Time	—	360	—		V_{GE} = 15V, R_G = 5.0Ω		
t_f	Fall Time	—	230	—		Energy losses include "tail" and		
E_{ts}	Total Switching Loss	—	4.5	—	mJ	diode reverse recovery.		
L_E	Internal Emitter Inductance	—	13	—	nH	Measured 5mm from package		
C_{ies}	Input Capacitance	—	2900	—	pF	V_{GE} = 0V		
C_{oes}	Output Capacitance	—	330	—		V_{CC} = 30V See Fig. 7		
C_{res}	Reverse Transfer Capacitance	—	40	—		f = 1.0MHz		
t_{rr}	Diode Reverse Recovery Time	—	50	75	ns	T_J = 25°C	See Fig.	
		—	105	160		T_J = 125°C	14	I_F = 25A
I_{rr}	Diode Peak Reverse Recovery Current	—	4.5	10	A	T_J = 25°C	See Fig.	
		—	8.0	15		T_J = 125°C	15	V_R = 200V
Q_{rr}	Diode Reverse Recovery Charge	—	112	375	nC	T_J = 25°C	See Fig.	
		—	420	1200		T_J = 125°C	16	di/dt = 200A/µs
$di_{(rec)M}/dt$	Diode Peak Rate of Fall of Recovery	—	250	—	A/µs	T_J = 25°C	See Fig.	
	During t_b	—	160	—		T_J = 125°C	17	

Notes:

① Repetitive rating; V_{GE}=20V, pulse width limited by max. junction temperature. (See fig. 20)

② V_{CC}=80%(V_{CES}), V_{GE}=20V, L=10µH, R_G= 5.0Ω, (See fig. 19)

③ Pulse width ≤ 80µs; duty factor ≤ 0.1%.

④ Pulse width 5.0µs, single shot.

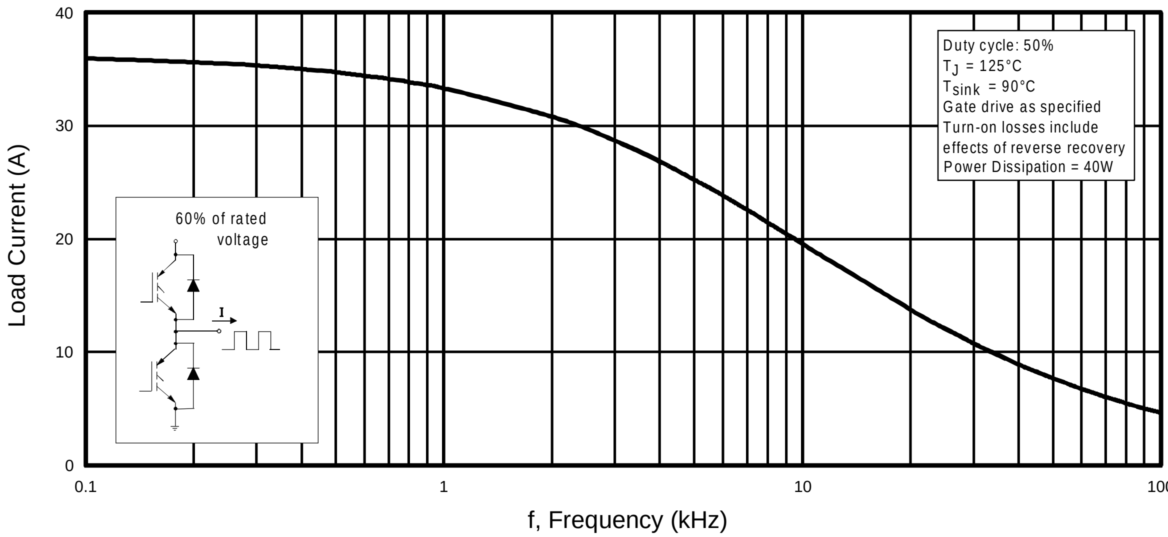


Fig. 1 - Typical Load Current vs. Frequency
(Load Current = I_{RMS} of fundamental)

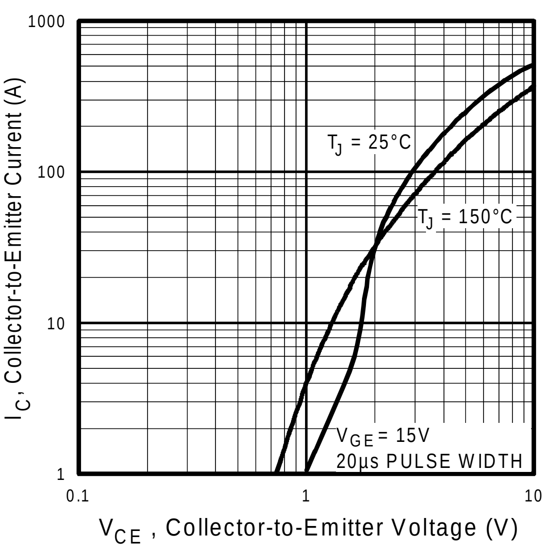


Fig. 2 - Typical Output Characteristics

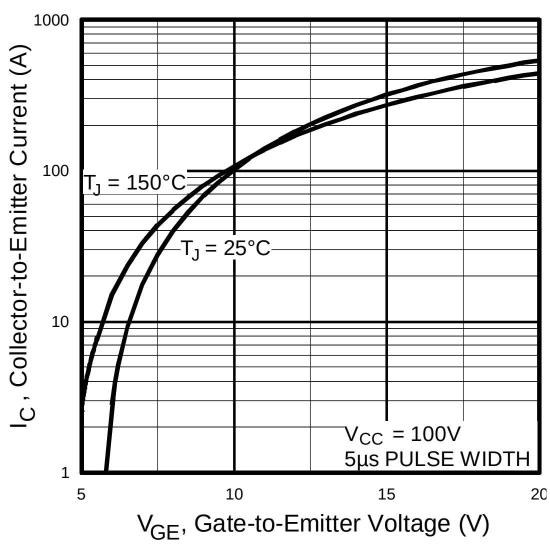


Fig. 3 - Typical Transfer Characteristics

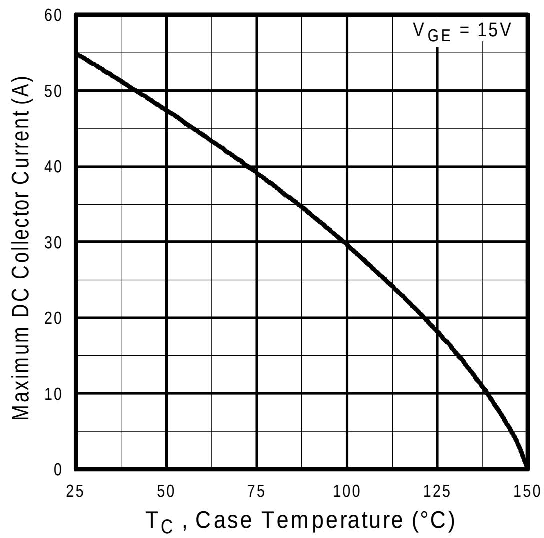


Fig. 4 - Maximum Collector Current vs. Case Temperature

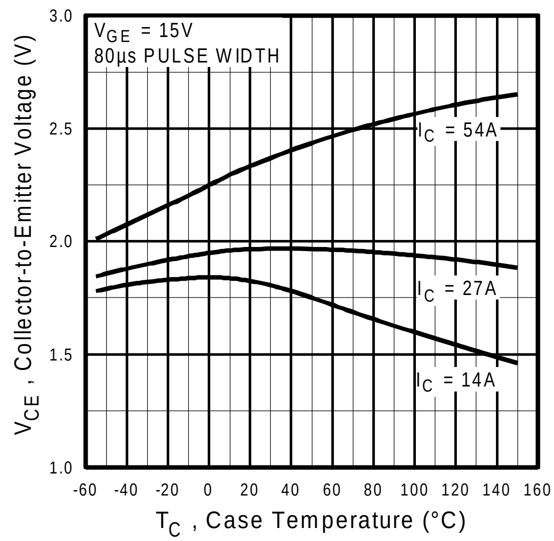


Fig. 5 - Collector-to-Emitter Voltage vs. Case Temperature

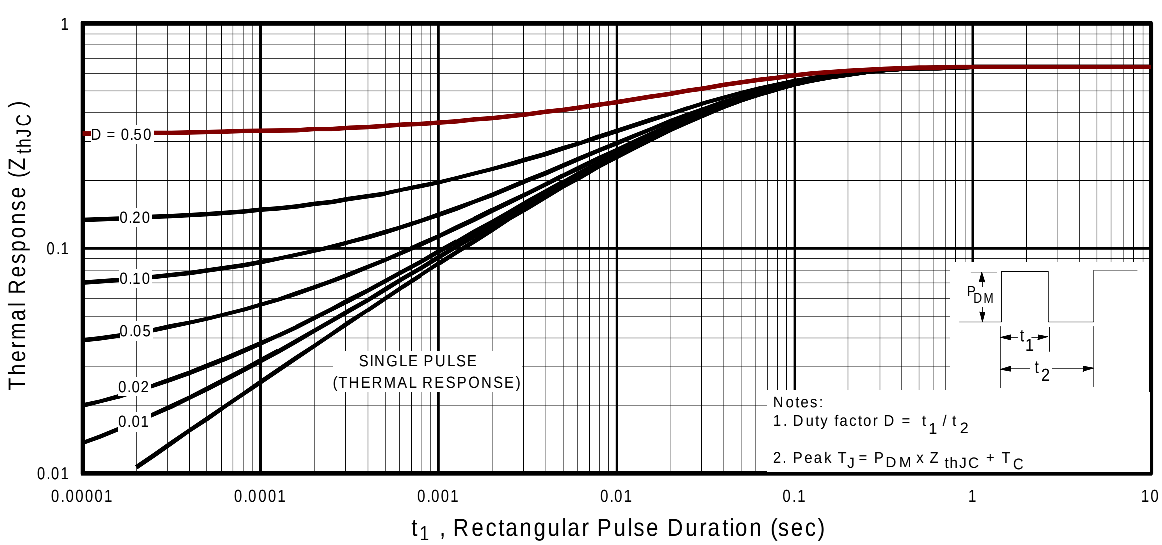


Fig. 6 - Maximum IGBT Effective Transient Thermal Impedance, Junction-to-Case

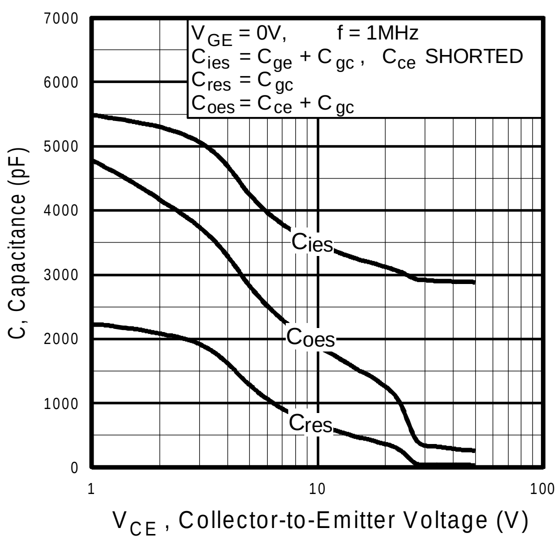


Fig. 7 - Typical Capacitance vs. Collector-to-Emitter Voltage

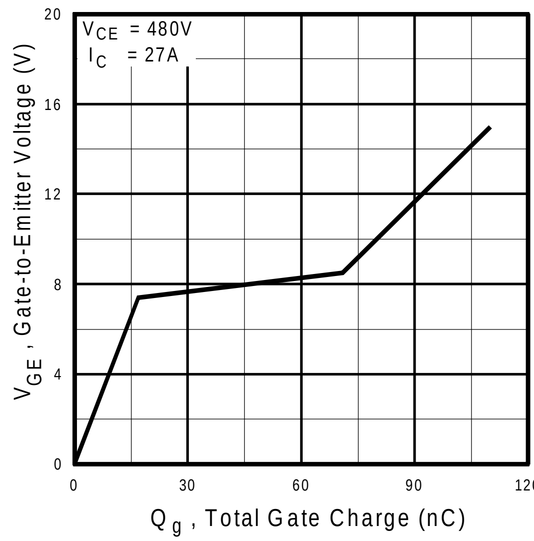


Fig. 8 - Typical Gate Charge vs. Gate-to-Emitter Voltage

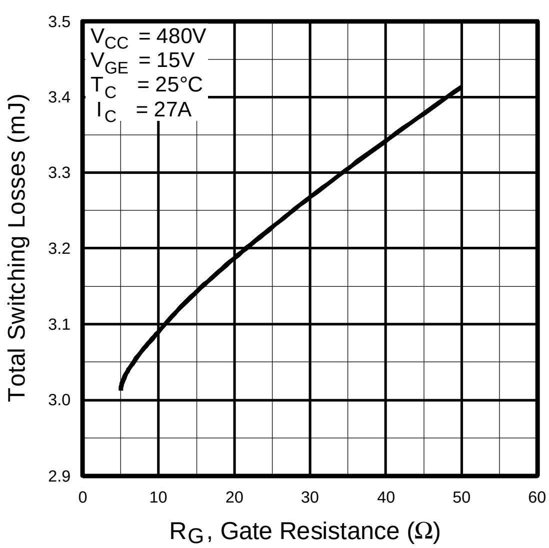


Fig. 9 - Typical Switching Losses vs. Gate Resistance

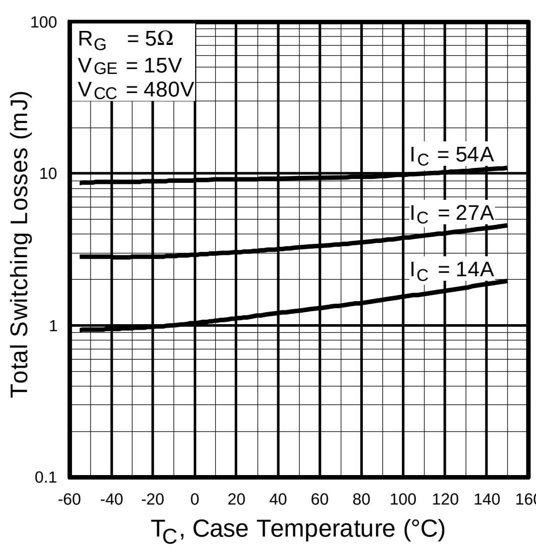


Fig. 10 - Typical Switching Losses vs. Case Temperature

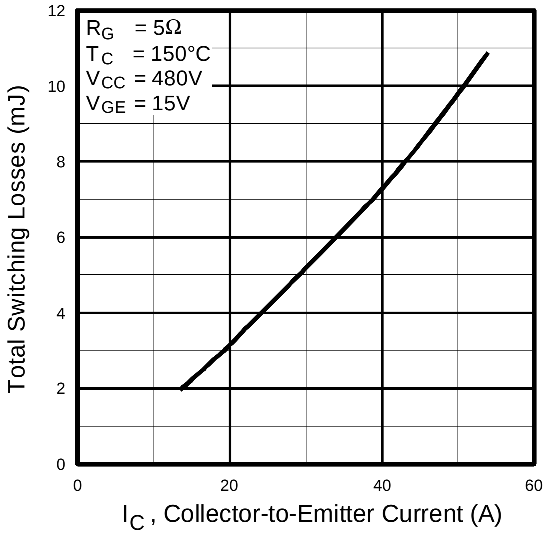


Fig. 11 - Typical Switching Losses vs. Collector-to-Emitter Current

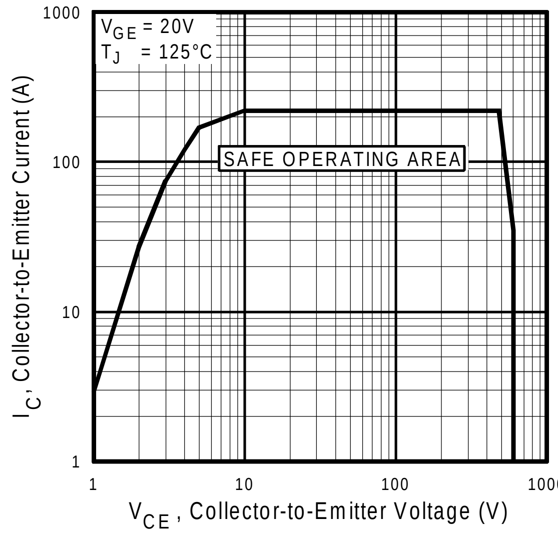


Fig. 12 - Turn-Off SOA

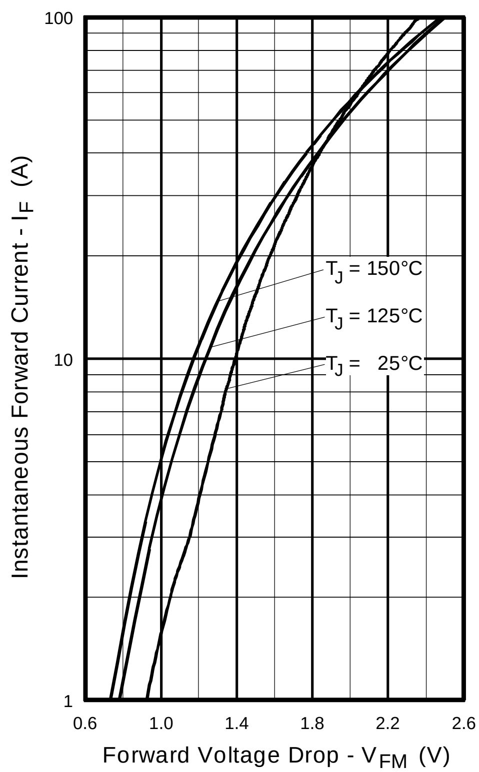


Fig. 13 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

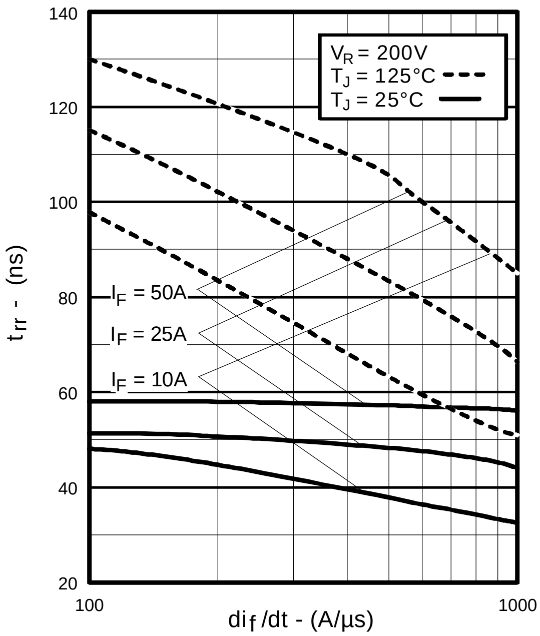


Fig. 14 - Typical Reverse Recovery vs. di_f/dt

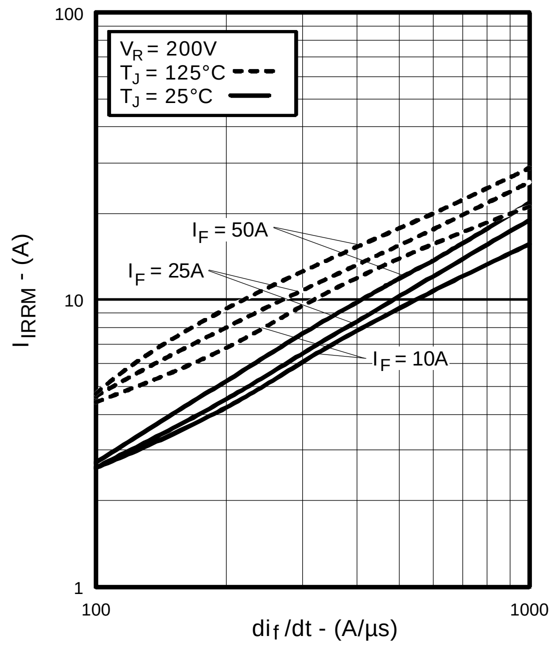


Fig. 15 - Typical Recovery Current vs. di_f/dt

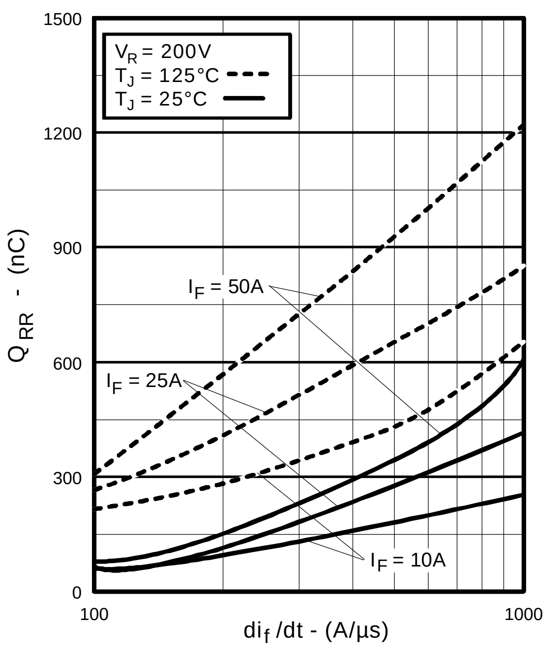


Fig. 16 - Typical Stored Charge vs. di_f/dt

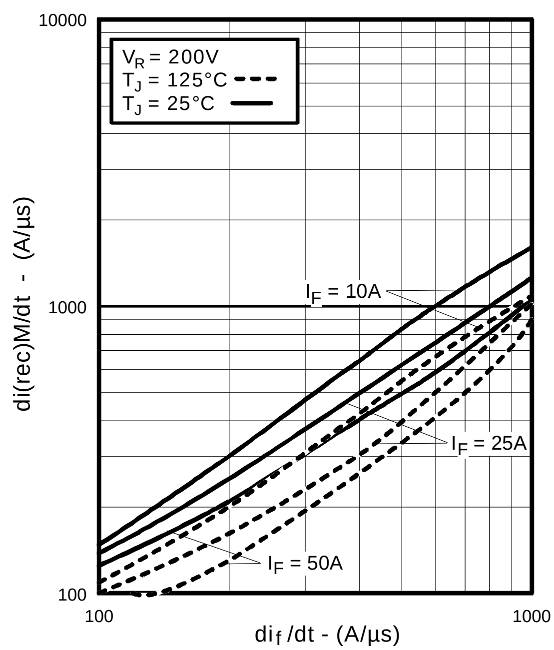


Fig. 17 - Typical $di_{(rec)M}/dt$ vs. di_f/dt

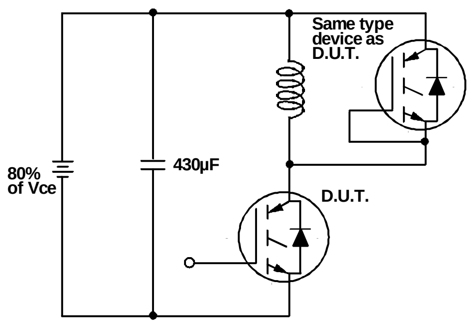


Fig. 18a - Test Circuit for Measurement of I_{LM}, E_{on}, $E_{off(diode)}$, t_{rr}, Q_{rr}, I_{rr}, $t_{d(on)}$, t_r, $t_{d(off)}$, t_f

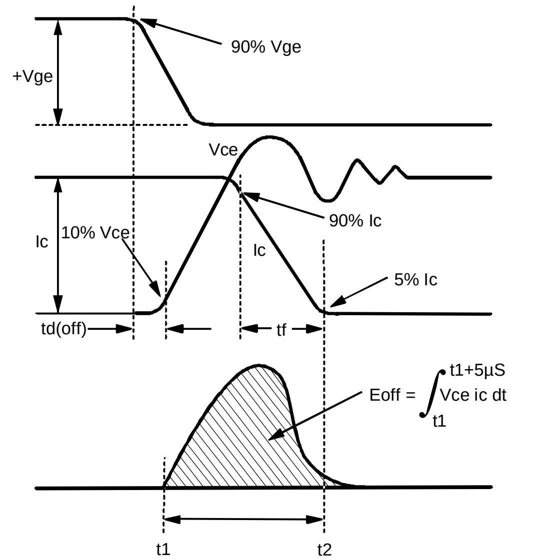


Fig. 18b - Test Waveforms for Circuit of Fig. 18a, Defining E_{off}, $t_{d(off)}$, t_f

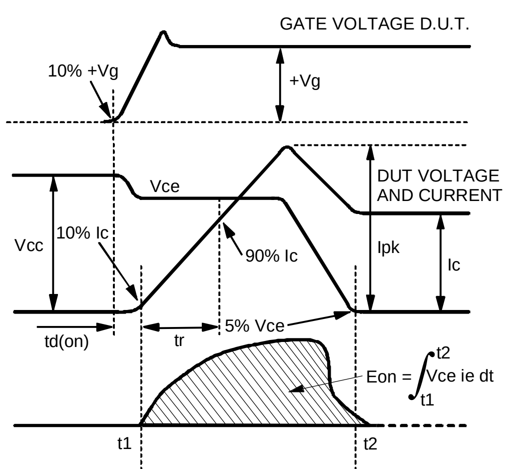


Fig. 18c - Test Waveforms for Circuit of Fig. 18a, Defining E_{on}, $t_{d(on)}$, t_r

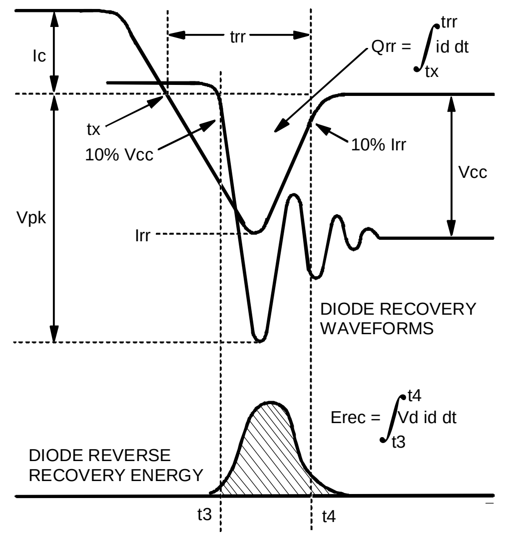


Fig. 18d - Test Waveforms for Circuit of Fig. 18a, Defining E_{rec}, t_{rr}, Q_{rr}, I_{rr}

Refer to Section D for the following:
Appendix D: Section D - page D-6

Fig. 18e - Macro Waveforms for Test Circuit of Fig. 18a
Fig. 19 - Clamped Inductive Load Test Circuit
Fig. 20 - Pulsed Collector Current Test Circuit

Package Outline 3 - JEDEC Outline TO-247AC **Section D - page D-13**

Note: For the most current drawings please refer to the IR website at:
http://www.irf.com/package/